



### 30V P-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C		
001/	15mΩ @ V <sub>GS</sub> = -10V	-39A		
-30V	25mΩ @ V <sub>GS</sub> = -5V	-20A		

### **Features and Benefits**

- Low Rds(ON) Ensures On-State Losses Are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies just 33% of The Board Area Occupied by SO-8 Enabling Smaller End Product
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen- and Antimony-Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. <a href="https://www.diodes.com/quality/product-definitions/">https://www.diodes.com/quality/product-definitions/</a>

## **Description and Applications**

This new generation MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

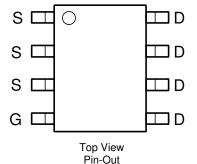
- Backlighting
- Power Management Functions
- DC-DC Converters

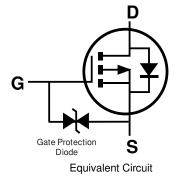
### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram Below
- Terminals: Finish—Matte Tin Annealed over Copper Lead-Frame.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)









Top View

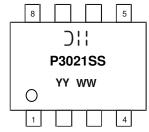
Ordering Information (Note 4)

Part Number	Case	Packaging
DMP3021SSS-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



⊃¦¦ = Manufacturer's Marking
 P3021SS = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Year (ex: 21 = 2021)
 WW or WW = Week (01 to 53)



# **Maximum Ratings** (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	-30	V
Gate-Source Voltage			$V_{GSS}$	±25	V
Continuous Drain Current (Note 6) VGS = -10V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lo	-10.4 -8.3	А
Continuous Drain Current (Note 7) VGS = -10V	Steady State	$T_C = +25$ °C $T_C = +70$ °C	lo	-39 -31	А
Maximum Continuous Body Diode Forward Current (Note 7)			Is	-3.2	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	-128	Α
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)			I <sub>SM</sub>	-128	Α
Avalanche Current (Note 8) L = 1mH			las	-13	Α
Avalanche Energy (Note 8) L = 1mH			Eas	84	mJ

# Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25°C	PD	1	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	127	°C/W
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25°C	PD	2.5	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	51	°C/W
Thermal Resistance, Junction to Case (Note 7)	Rejc	3.6	°C/W	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

### Electrical Characteristics (@ TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BVDSS	-30	l	_	٧	$V_{GS} = 0V, I_{D} = -250\mu A$
Zero Gate Voltage Drain Current	IDSS	_	_	-1	μΑ	$V_{DS} = -30V$ , $V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$V_{GS(TH)}$	-1.0	-	-2.5	<b>V</b>	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$
Static Drain-Source On-Resistance	Provesti:	_	10.7	15	mΩ	$V_{GS} = -10V, I_{D} = -8A$
Static Dialii-Source Off-Nesistance	RDS(ON)	_	16	25	11122	$V_{GS} = -5V$ , $I_D = -5A$
Diode Forward Voltage	$V_{SD}$	_	-0.7	-1.2	٧	$V_{GS} = 0V, I_{S} = -1A$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	Ciss	_	1799	_	pF	V 45V V 0V
Output Capacitance	Coss	_	259	_	pF	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, -f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	225	_	pF	1 = 1.0IVIH2
Gate Resistance	Rg	_	3.2	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (VGS = -4.5V)	Qg	_	17.4	_	nC	
Total Gate Charge (VGS = -10V)	Qg		34	_	nC	\/ 15\/ I- 10A
Gate-Source Charge	Qgs	_	5.1	_	nC	$V_{DS} = -15V, I_{D} = -10A$
Gate-Drain Charge	$Q_{gd}$	_	8.4	_	nC	
Turn-On Delay Time	td(ON)	_	6.5	_	ns	
Turn-On Rise Time	t <sub>R</sub>	_	18.3	_	ns	$V_{DD} = -15V$ , $V_{GS} = -10V$ ,
Turn-Off Delay Time	tD(OFF)	_	35.8	_	ns	$R_G = 3\Omega$ , $I_D = -10A$
Turn-Off Fall Time	tF	_	23.7	_	ns	
Reverse Recovery Time	trr	_	14.9	_	ns	10 0A d1/dt 500A/vo
Reverse Recovery Charge	QRR		15.3	_	nC	Is = -8A, dI/dt = 500A/μs

Notes: 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
7. Thermal resistance from junction to soldering point (on the exposed drain pad).

8. I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep  $T_J$  = +25°C.

9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to product testing.



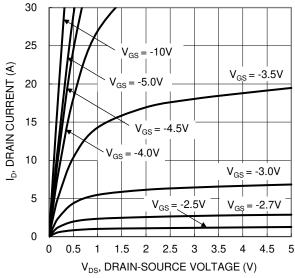


Figure 1. Typical Output Characteristic

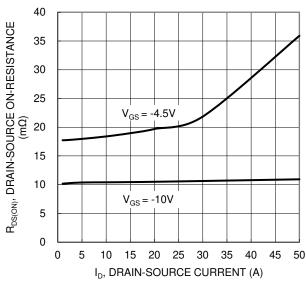


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

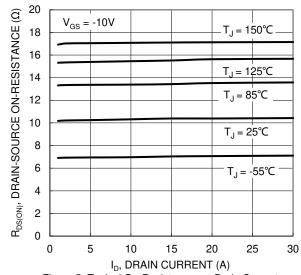


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

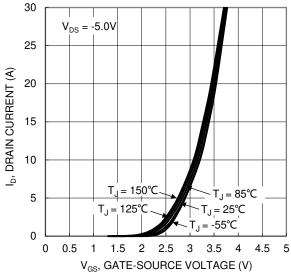


Figure 2. Typical Transfer Characteristic

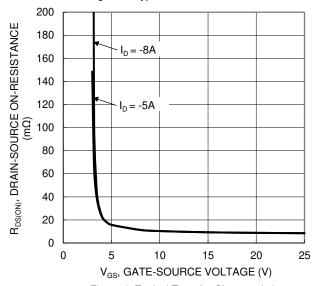


Figure 4. Typical Transfer Characteristic

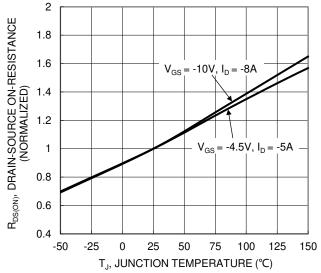


Figure 6. On-Resistance Variation with Junction Temperature



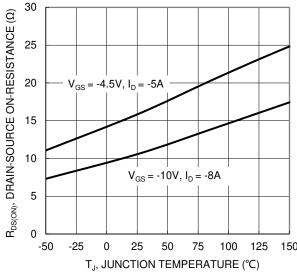
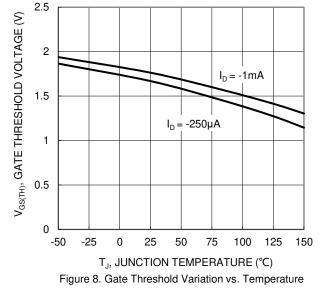


Figure 7. On-Resistance Variation with Temperature



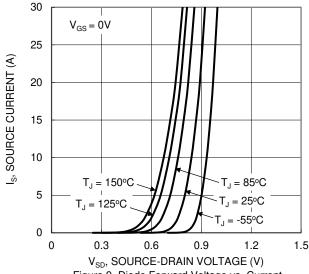
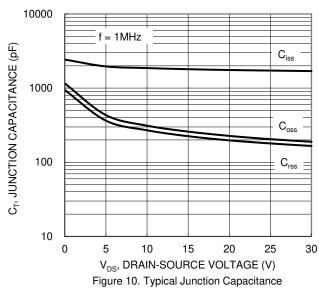


Figure 9. Diode Forward Voltage vs. Current



10 8 6 4 V<sub>DS</sub> = -15V, I<sub>D</sub> = -10A 2 0 0 10 20 30 40 50 Q<sub>g</sub> (nC) Figure 11. Gate Charge

10 ID, DRAIN CURRENT (A)  $\begin{array}{c|c} P_W = 1ms \\ \hline P_W = 10ms \\ \hline T_{J(Max)} = 150^{\circ}C \\ \hline T_C = 25^{\circ}C \\ \hline \end{array}$ 100ms 0.1 Single Pulse = 1s = 10sDUT on 1\*MRP Board DC  $V_{GS} = -10V$ 0.01 0.1 10 100 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area

V<sub>GS</sub> (V)

100

July 2021



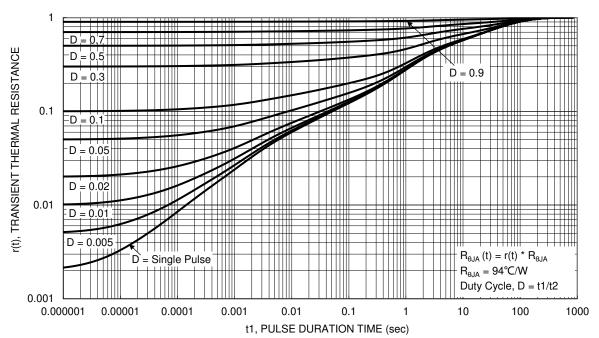
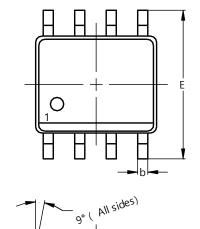


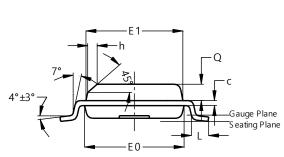
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.





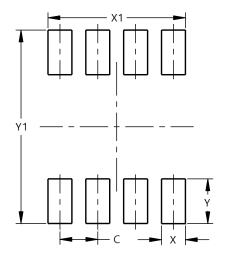
SO-8

SO-8					
Dim	Min	Max	Тур		
Α	1.40	1.50	1.45		
<b>A</b> 1	0.10	0.20	0.15		
p	0.30	0.50	0.40		
O	0.15	0.25	0.20		
D	4.85	4.95	4.90		
Е	5.90	6.10	6.00		
E1	3.80	3.90	3.85		
E0	3.85	3.95	3.90		
е	_	_	1.27		
h		_	0.35		
Г	0.62	0.82	0.72		
Ø	0.60	0.70	0.65		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### SO-8



Dimensions	Value (in mm)		
С	1.27		
Х	0.802		
X1	4.612		
Y	1.505		
V1	6.50		



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